

## Product Summary

$BV_{DSS}$	$R_{DS(ON)} \text{ max}$	$I_D$ $T_A = +25^\circ\text{C}$
-12V	31mΩ@ $V_{GS} = -4.5\text{V}$	-5.2A
	45mΩ@ $V_{GS} = -2.5\text{V}$	-4.3A

## Description and Applications

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

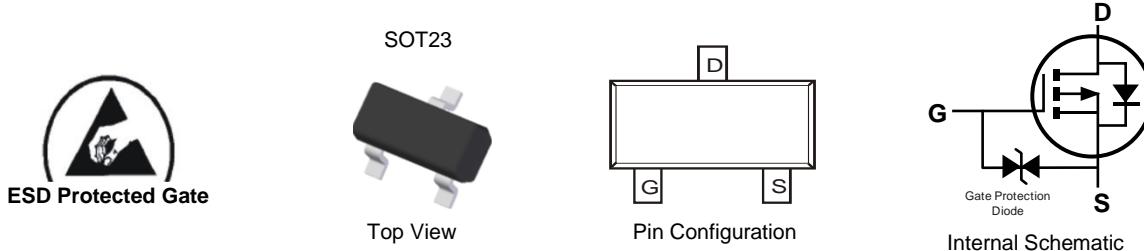
- DC-DC Converters
- BLDC Motors
- Load Switch

## Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **ESD Protected**
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

## Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208(e3)
- Weight: 0.009 grams (Approximate)

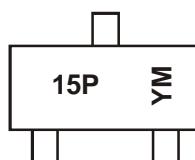


## Ordering Information (Note 5)

Part Number	Compliance	Case	Packaging
DMP1045UQ-7	Automotive	SOT23	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to <https://www.diodes.com/quality/product-compliance-definitions/>.
  5. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



15P = Marking Code  
YM = Date Code Marking  
Y = Year (ex: E = 2017)  
M = Month (ex: 9 = September)

### Date Code Key

Year	2013		~	2017		2018		2019		2020		
Code	A		~	E	F	G	H					
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			$V_{DSS}$	-12	V
Gate-Source Voltage			$V_{GSS}$	$\pm 8$	V
Continuous Drain Current (Note 6) $V_{GS} = -4.5\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	$I_D$	-4.0 -3.1	A
Continuous Drain Current (Note 6) $V_{GS} = -2.5\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	$I_D$	-3.3 -2.6	A
Continuous Drain Current (Note 7) $V_{GS} = -4.5\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	$I_D$	-5.2 -4.2	A
Continuous Drain Current (Note 7) $V_{GS} = -2.5\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	$I_D$	-4.3 -3.4	A
Maximum Continuous Body Diode Forward Current (Note 7)			$I_S$	-2	A
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%) (Note 6)			$I_{DM}$	-40	A

**Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 6)	$P_D$	0.8	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	168	°C/W
Total Power Dissipation (Note 7)	$P_D$	1.3	W
Thermal Resistance, Junction to Ambient (Note 7)	$R_{\theta JA}$	99	°C/W
Thermal Resistance, Junction to Case (Note 7)	$R_{\theta JC}$	14.8	°C/W
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	°C

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 8)</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	-12	—	—	V	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$
Zero Gate Voltage Drain Current $T_J = +25^\circ\text{C}$	$I_{DSS}$	—	—	-1.0	μA	$V_{DS} = -12\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	$I_{GSS}$	—	—	$\pm 10$	μA	$V_{GS} = \pm 8\text{V}, V_{DS} = 0\text{V}$
<b>ON CHARACTERISTICS (Note 8)</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	-0.3	-0.55	-1.0	V	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	26	31	mΩ	$V_{GS} = -4.5\text{V}, I_D = -4.0\text{A}$
			31	45		$V_{GS} = -2.5\text{V}, I_D = -3.5\text{A}$
			45	75		$V_{GS} = -1.8\text{V}, I_D = -2.7\text{A}$
Forward Transfer Admittance	$ Y_{fs} $	—	12	—	S	$V_{DS} = -5\text{V}, I_D = -4\text{A}$
Diode Forward Voltage	$V_{SD}$	—	-0.6	—	V	$V_{GS} = 0\text{V}, I_S = -1\text{A}$
<b>DYNAMIC CHARACTERISTICS (Note 9)</b>						
Input Capacitance	$C_{iss}$	—	1357	—	pF	$V_{DS} = -10\text{V}, V_{GS} = 0\text{V}$ $f = 1.0\text{MHz}$
Output Capacitance	$C_{oss}$	—	504	—	pF	
Reverse Transfer Capacitance	$C_{rss}$	—	235	—	pF	
Gate Resistance	$R_g$	—	14.1	—	Ω	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
<b>SWITCHING CHARACTERISTICS (Note 9)</b>						
Total Gate Charge	$Q_g$	—	15.8	—	nC	$V_{GS} = -4.5\text{V}, V_{DS} = -10\text{V}, I_D = -4\text{A}$
Gate-Source Charge	$Q_{gs}$	—	2.0	—	nC	
Gate-Drain Charge	$Q_{gd}$	—	3.9	—	nC	
Turn-On Delay Time	$t_{D(ON)}$	—	15.7	—	ns	$V_{DS} = -10\text{V}, V_{GS} = -4.5\text{V}, R_L = 2.5\Omega, R_G = 3.0\Omega$
Turn-On Rise Time	$t_R$	—	23.3	—	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	—	91.2	—	ns	
Turn-Off Fall Time	$t_F$	—	106.9	—	ns	

- Notes:
- 6. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
  - 7. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate.
  - 8. Short duration pulse test used to minimize self-heating effect.
  - 9. Guaranteed by design. Not subject to production testing.

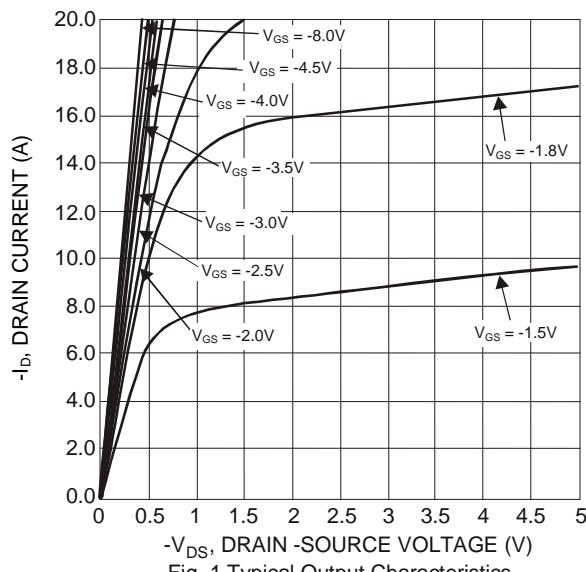


Fig. 1 Typical Output Characteristics

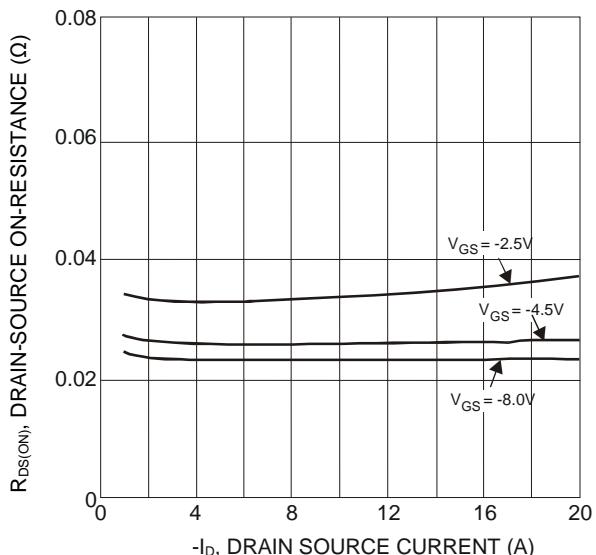


Fig. 3 Typical On-Resistance vs.  
Drain Current and Gate Voltage

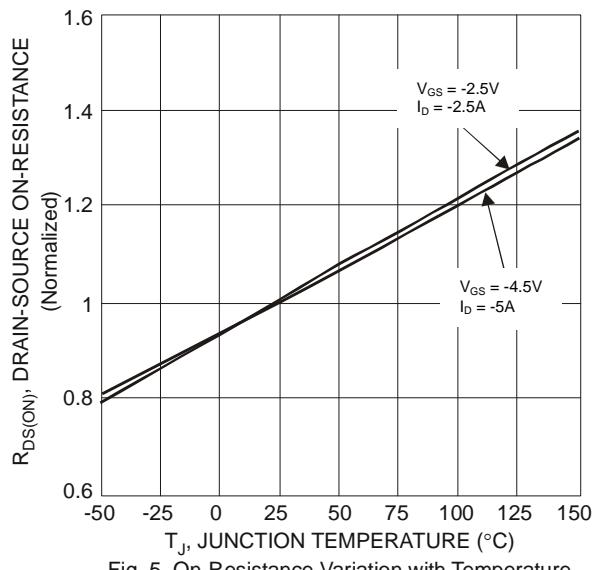


Fig. 5 On-Resistance Variation with Temperature

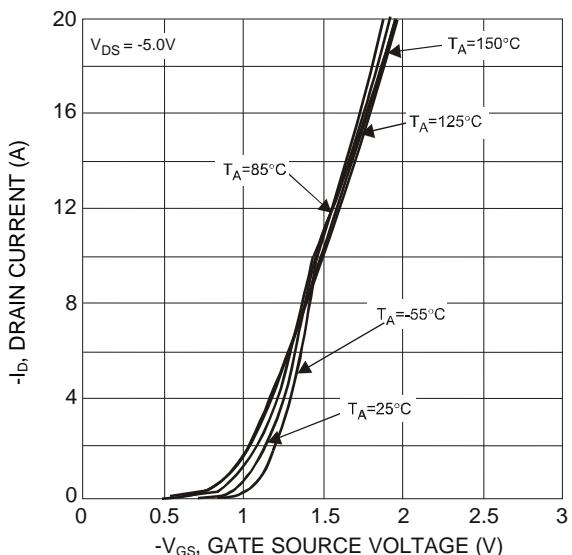


Fig. 2 Typical Transfer Characteristics

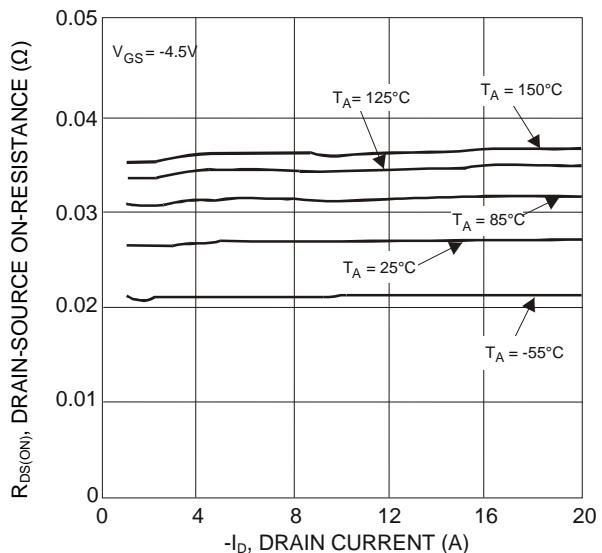


Fig. 4 Typical On-Resistance vs.  
Drain Current and Temperature

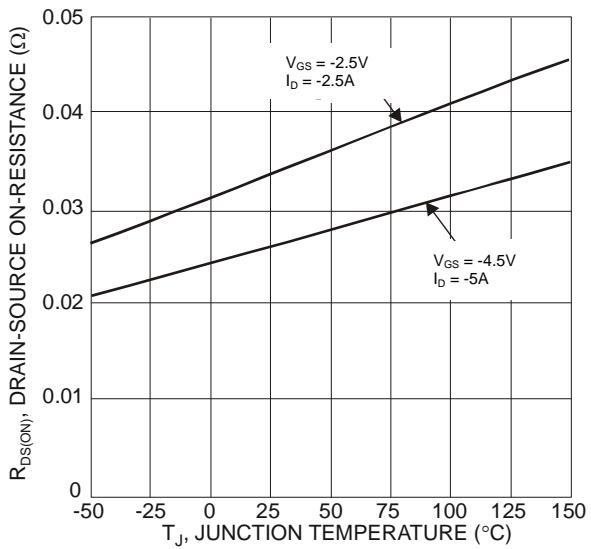


Fig. 6 On-Resistance Variation with Temperature

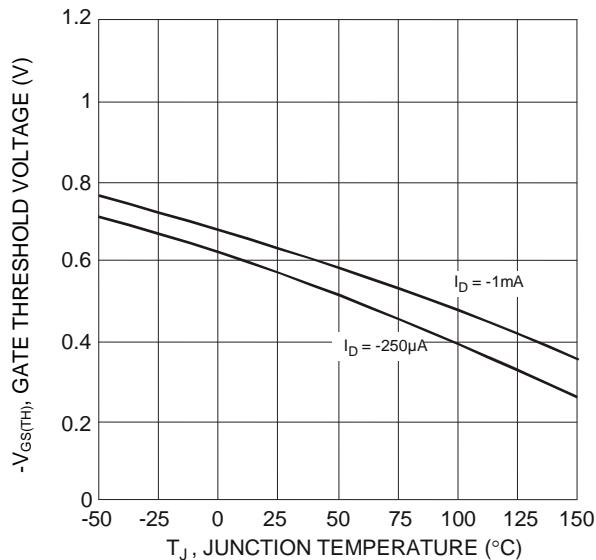


Fig. 7 Gate Threshold Variation vs. Junction Temperature

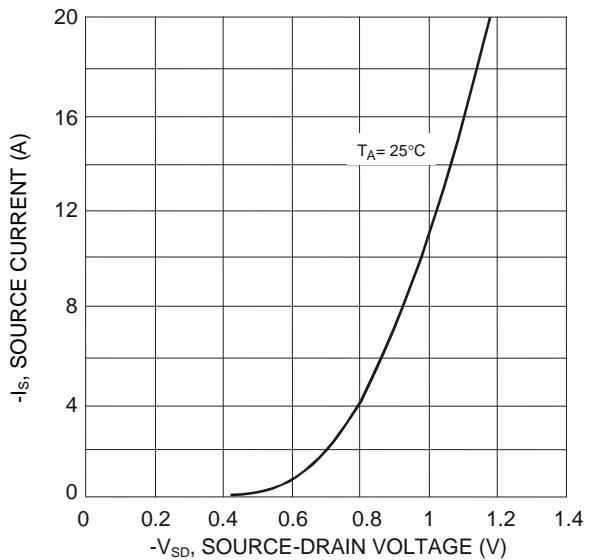


Fig. 8 Diode Forward Voltage vs. Current

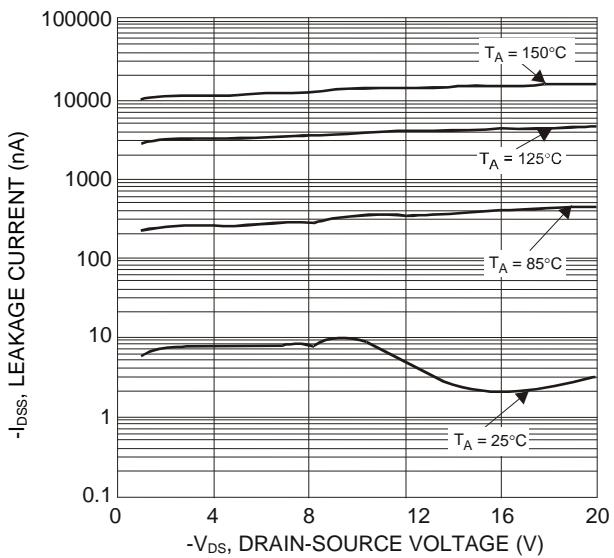


Fig. 9 Typical Drain-Source Leakage Current vs. Voltage

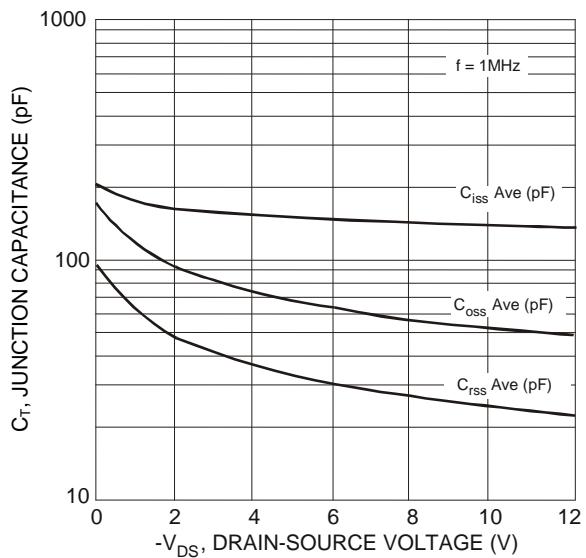


Fig. 10 Typical Junction Capacitance

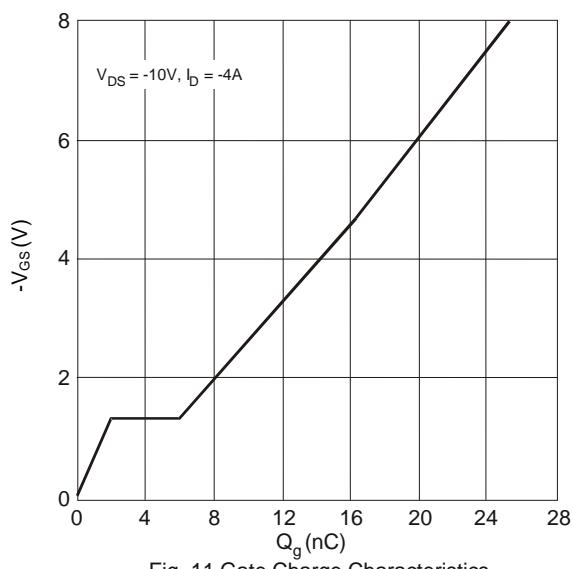


Fig. 11 Gate Charge Characteristics

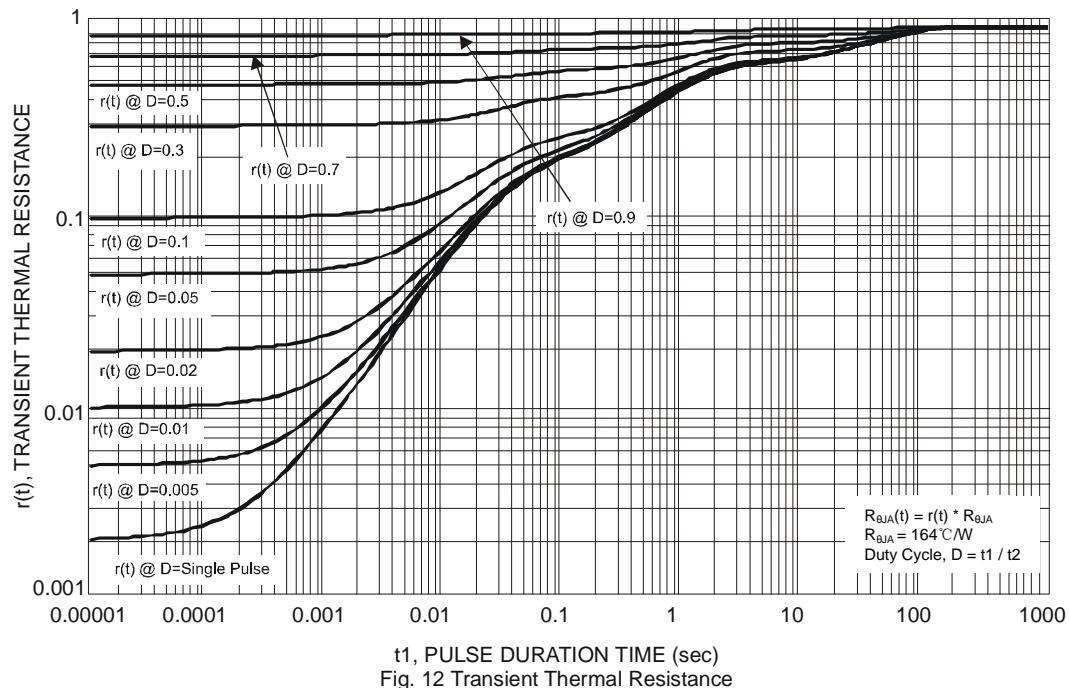
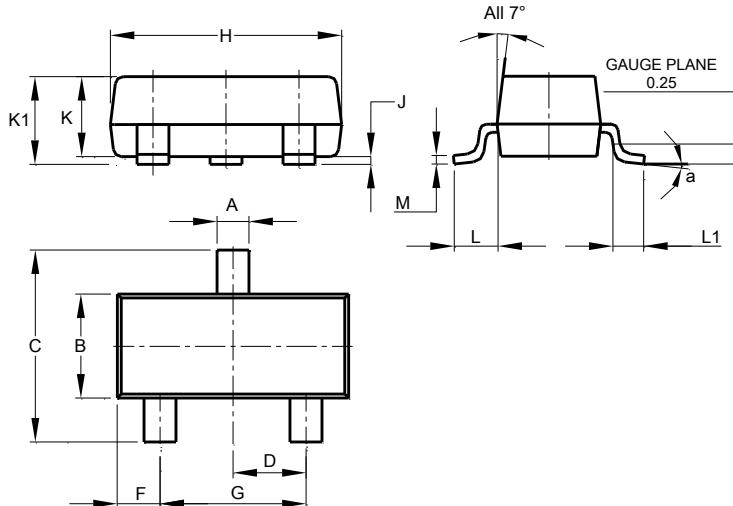


Fig. 12 Transient Thermal Resistance

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT23



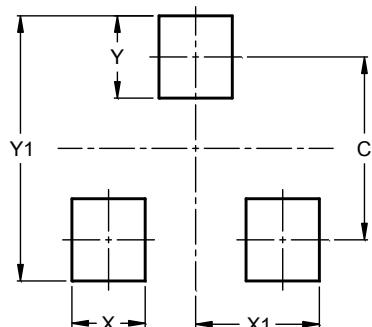
SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--

All Dimensions in mm

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT23



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

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